

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT7509570

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
DUANE WILCOXEN	03/12/2020
CHIAO-SHUN CHUANG	03/12/2020
RAIN LIU	03/12/2020
THOMAS TSAI	03/12/2020
WILL ZHANG	03/12/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	DIODES INCORPORATED
<b>Street Address:</b>	4949 HEDGCOXE ROAD
<b>City:</b>	PLANO
<b>State/Country:</b>	TEXAS
<b>Postal Code:</b>	75024
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16816321
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	9727313551
<b>Email:</b>	hardeep_kaur@diodes.com
<b>Correspondent Name:</b>	DIODES INCORPORATED
<b>Address Line 1:</b>	4949 HEDGCOXE ROAD
<b>Address Line 4:</b>	PLANO, TEXAS 75024
<b>ATTORNEY DOCKET NUMBER:</b>	DI-2019-016-US
<b>NAME OF SUBMITTER:</b>	HARDEEP KAUR
<b>SIGNATURE:</b>	/Hardeep Kaur/
<b>DATE SIGNED:</b>	08/29/2022
<b>Total Attachments: 5</b>	
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source=Assignment#page2.tif  
source=Assignment#page3.tif  
source=Assignment#page4.tif  
source=Assignment#page5.tif

**ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made.

WHEREAS, DIODES INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 4949 Hedgcoxe Road, Suite 200, Plano, Texas 75024, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon, as well as to U.S. Provisional Application No(s) \_\_\_\_\_ filed on \_\_\_\_\_

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign unto the said DIODES INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in and to the said application(s) and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof, and I hereby authorize and request the Patent and Trademark Office to issue all patents for said invention, or patents resulting therefrom, to the said DIODES INCORPORATED, as assignee of my entire right, title and interest

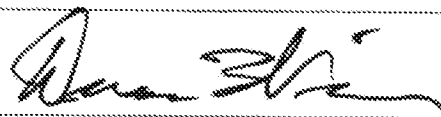
I also hereby sell and assign to DIODES INCORPORATED, its successors and assigns, my corresponding rights to the invention disclosed in said application in all other countries of the world, including the right to claim priority, file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such rights.

I hereby further agree that I will communicate to said DIODES INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said DIODES INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the nonprovisional application number and filing date hereinbelow.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year:

TITLE	A THINNED SEMICONDUCTOR CHIP WITH EDGE SUPPORT		
NONPROVISIONAL APPLICATION NO	16816321	FILING DATE	MAR. 12, 2020

SIGNATURE OF INVENTOR	
PRINTED NAME OF INVENTOR	Duane Wilcoxon
DATE	03/05/20
RESIDENCE (CITY AND STATE OR COUNTRY)	7704 KILBRIDE CIRCLE DALLAS, TX 75248

After recording, return Assignment to:

DIODES INCORPORATED  
4949 Hedgcoxe Road, Suite 200  
Plano, TX 75024

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TITLE	A THINNED SEMICONDUCTOR CHIP WITH EDGE SUPPORT		
NONPROVISIONAL APPLICATION NO.	16816321	FILING DATE	MAR. 12, 2020
SIGNATURE OF INVENTOR	Chiao-Shun Chuang		
PRINTED NAME OF INVENTOR	Chiao-Shun Chuang		
DATE	2020.03.11		
RESIDENCE (CITY AND STATE OR COUNTRY)	18F, No.122, Sec 2, Fuxing 3rd RD, Zhubei City, Hsinchu County, 302, Taiwan		

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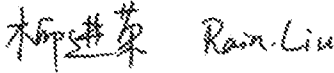
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TITLE	A THINNED SEMICONDUCTOR CHIP WITH EDGE SUPPORT		
NONPROVISIONAL APPLICATION NO.	16816321	FILING DATE	Mar. 12, 2020

SIGNATURE OF INVENTOR	 Rain Liu
PRINTED NAME OF INVENTOR	柳进荣 Rain Liu
DATE	3/6/2020
RESIDENCE (CITY AND STATE OR COUNTRY)	566 Jinliang Road, Pidu Zone, Chengdu, Sichuan, PRC

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DIODES INCORPORATED  
4949 Hedgcoxe Road, Suite 200  
Plano, TX 75024

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TITLE	A THINNED SEMICONDUCTOR CHIP WITH EDGE SUPPORT		
NONPROVISIONAL APPLICATION NO.	168/6321	FILING DATE	MAY 12, 2020
SIGNATURE OF INVENTOR	Thomas Tsai		
PRINTED NAME OF INVENTOR	Thomas Tsai		
DATE	03/06/20		
RESIDENCE (CITY AND STATE OR COUNTRY)	No. 27, Ln. 315, Xuefu E. Rd., Zhudong Township, Hsinchu County 310, Taiwan (R.O.C.)		

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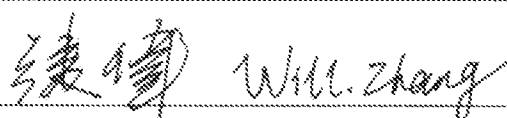
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NONPROVISIONAL APPLICATION NO.	16816321	FILING DATE	Mar. 12, 2020

SIGNATURE OF INVENTOR			
PRINTED NAME OF INVENTOR	张伟 WILL ZHANG		
DATE	3/6/2020		
RESIDENCE (CITY AND STATE OR COUNTRY)	55 Huangtu Street, Qingyang Zone, Chengdu, Sichuan, PRC		

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4949 Hedgcoxe Road, Suite 200  
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